Renesas Electronics America Inc - R5F211B2NP#U0 Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, SIO, SSU, UART/USART
Peripherals	LED, POR, Voltage Detect, WDT
Number of I/O	13
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-WFQFN Exposed Pad
Supplier Device Package	28-HWQFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f211b2np-u0

R8C/1A Group, R8C/1B Group

SINGLE-CHIP 16-BIT CMOS MICROCOMPUTER

REJ03B0144-0140
Rev.1.40
Dec 08, 2006

1. Overview

These MCUs are fabricated using the high-performance silicon gate CMOS process, embedding the R8C/Tiny Series CPU core, and is packaged in a 20-pin molded-plastic LSSOP, SDIP or a 28-pin plastic molded-HWQFN. It implements sophisticated instructions for a high level of instruction efficiency. With 1 Mbyte of address space, they are capable of executing instructions at high speed.
Furthermore, the R8C/1B Group has on-chip data flash ROM (1 KB × 2 blocks).
The difference between the R8C/1A Group and R8C/1B Group is only the presence or absence of data flash ROM. Their peripheral functions are the same.

1.1 Applications

Electric household appliances, office equipment, housing equipment (sensors, security systems), portable equipment, general industrial equipment, audio equipment, etc.

1.4 Product Information

Table 1.3 lists Product Information for R8C/1A Group and Table 1.4 lists Product Information for R8C/1B Group.

Table 1.3 Product Information for R8C/1A Group **Current of October 2006**

Type No.	ROM Capacity	RAM Capacity	Package Type	Remarks
R5F211A1SP	4 Kbytes	384 bytes	PLSP0020JB-A	
R5F211A2SP	8 Kbytes	512 bytes	PLSP0020JB-A	
R5F211A3SP	12 Kbytes	768 bytes	PLSP0020JB-A	
R5F211A4SP	16 Kbytes	1 Kbyte	PLSP0020JB-A	
R5F211A1DSP	4 Kbytes	384 bytes	PLSP0020JB-A	D version
R5F211A2DSP	8 Kbytes	512 bytes	PLSP0020JB-A	
R5F211A3DSP	12 Kbytes	768 bytes	PLSP0020JB-A	
R5F211A4DSP	16 Kbytes	1 Kbyte	PLSP0020JB-A	
R5F211A1DD	4 Kbytes	384 bytes	PRDP0020BA-A	
R5F211A2DD	8 Kbytes	512 bytes	PRDP0020BA-A	
R5F211A3DD	12 Kbytes	768 bytes	PRDP0020BA-A	
R5F211A4DD	16 Kbytes	1 Kbyte	PRDP0020BA-A	
R5F211A2NP	8 Kbytes	512 bytes	PWQN0028KA-B	
R5F211A3NP	12 Kbytes	768 bytes	PWQN0028KA-B	
R5F211A4NP	16 Kbytes	1 Kbyte	PWQN0028KA-B	
R5F211A1XXXSP	4 Kbytes	384 bytes	PLSP0020JB-A	Factory programming product (1)
R5F211A2XXXSP	8 Kbytes	512 bytes	PLSP0020JB-A	
R5F211A3XXXSP	12 Kbytes	768 bytes	PLSP0020JB-A	
R5F211A4XXXSP	16 Kbytes	1 Kbyte	PLSP0020JB-A	
R5F211A1DXXXSP	4 Kbytes	384 bytes	PLSP0020JB-A	D version
R5F211A2DXXXSP	8 Kbytes	512 bytes	PLSP0020JB-A	
R5F211A3DXXXSP	12 Kbytes	768 bytes	PLSP0020JB-A	
R5F211A4DXXXSP	16 Kbytes	1 Kbyte	PLSP0020JB-A	
R5F211A1XXXDD	4 Kbytes	384 bytes	PRDP0020BA-A	Factory programming product (1)
R5F211A2XXXDD	8 Kbytes	512 bytes	PRDP0020BA-A	
R5F211A3XXXDD	12 Kbytes	768 bytes	PRDP0020BA-A	
R5F211A4XXXDD	16 Kbytes	1 Kbyte	PRDP0020BA-A	
R5F211A2XXXNP	8 Kbytes	512 bytes	PWQN0028KA-B	
R5F211A3XXXNP	12 Kbytes	768 bytes	PWQN0028KA-B	
R5F211A4XXXNP	16 Kbytes	1 Kbyte	PWQN0028KA-B	

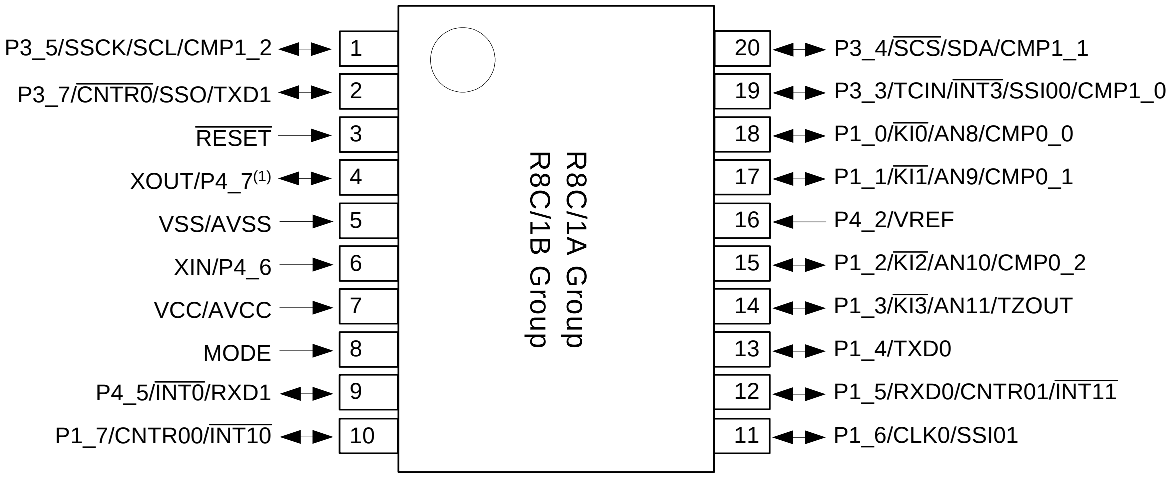
NOTE:

1. The user ROM is programmed before shipment.

1.5 Pin Assignments

Figure 1.4 shows Pin Assignments for PLSP0020JB-A Package (Top View), Figure 1.5 shows Pin Assignments for PRDP0020BA-A Package (Top View) and Figure 1.6 shows Pin Assignments for PWQN0028KA-B Package (Top View).

PIN assignments (top view)



NOTE:
1. P4_7 is an input-only port.

Package: PLSP0020JB-A (20P2F-A)

Figure 1.4 Pin Assignments for PLSP0020JB-A Package (Top View)

Table 1.6 Pin Name Information by Pin Number of PLSP0020JB-A, PRDP0020BA-A Packages

Pin Number	Control Pin	Port	I/O Pin Functions for Peripheral Modules					
			Interrupt	Timer	Serial Interface	Clock Synchronous Serial I/O with Chip Select	I^2C bus Interface	A/D Converter
1		P3_5		CMP1_2		SSCK	SCL	
2		P3_7		$\overline{\text{CNTR0}}$	TXD1	SSO		
3	$\overline{\text{RESET}}$							
4	XOUT	P4_7						
5	VSS/AVSS							
6	XIN	P4_6						
7	VCC/AVCC							
8	MODE							
9		P4_5	$\overline{\text{INT0}}$		RXD1			
10		P1_7	$\overline{\text{INT10}}$	CNTR00				
11		P1_6			CLK0	SSI01		
12		P1_5	$\overline{\text{INT11}}$	CNTR01	RXD0			
13		P1_4			TXD0			
14		P1_3	$\overline{\text{KI3}}$	TZOUT				AN11
15		P1_2	$\overline{\text{KI2}}$	CMP0_2				AN10
16	VREF	P4_2						
17		P1_1	$\overline{\text{KI1}}$	CMP0_1				AN9
18		P1_0	$\overline{\text{KI0}}$	CMP0_0				AN8
19		P3_3	$\overline{\text{INT3}}$	TCIN/ CMP1_0		SSI00		
20		P3_4		CMP1_1		$\overline{\text{SCS}}$	SDA	

Table 1.7 Pin Name Information by Pin Number of PWQN0028KA-B Package

Pin Number	Control Pin	Port	I/O Pin Functions for Peripheral Modules					
			Interrupt	Timer	Serial Interface	Clock Synchronous Serial I/O with Chip Select	I^2C bus Interface	A/D Converter
1	NC							
2	XOUT	P4_7						
3	VSS/AVSS							
4	NC							
5	NC							
6	XIN	P4_6						
7	NC							
8	VCC/AVCC							
9	MODE							
10		P4_5	$\overline{\text{INT0}}$		RXD1			
11		P1_7	$\overline{\text{INT10}}$	CNTR00				
12		P1_6			CLK0	SSI01		
13		P1_5	$\overline{\text{INT11}}$	CNTR01	RXD0			
14		P1_4			TXD0			
15	NC							
16		P1_3	$\overline{\text{KI3}}$	TZOUT				AN11
17		P1_2	$\overline{\text{KI2}}$	CMP0_2				AN10
18	NC							
19	NC							
20	VREF	P4_2						
21	NC							
22		P1_1	$\overline{\text{KI1}}$	CMP0_1				AN9
23		P1_0	$\overline{\text{KI0}}$	CMP0_0				AN8
24		P3_3	$\overline{\text{INT3}}$	TCIN/CMP1_0		SSI00		
25		P3_4		CMP1_1		$\overline{\text{SCS}}$	SDA	
26		P3_5		CMP1_2		SSCK	SCL	
27		P3_7		$\overline{\text{CNTR0}}$	TXD1	SSO		
28	$\overline{\text{RESET}}$							

2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts.
Interrupts are disabled when the I flag is set to 0, and are enabled when the I flag is set to 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to 0; USP is selected when the U flag is set to 1.
The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide, assigns processor interrupt priority levels from level 0 to level 7.
If a requested interrupt has higher priority than IPL, the interrupt is enabled.

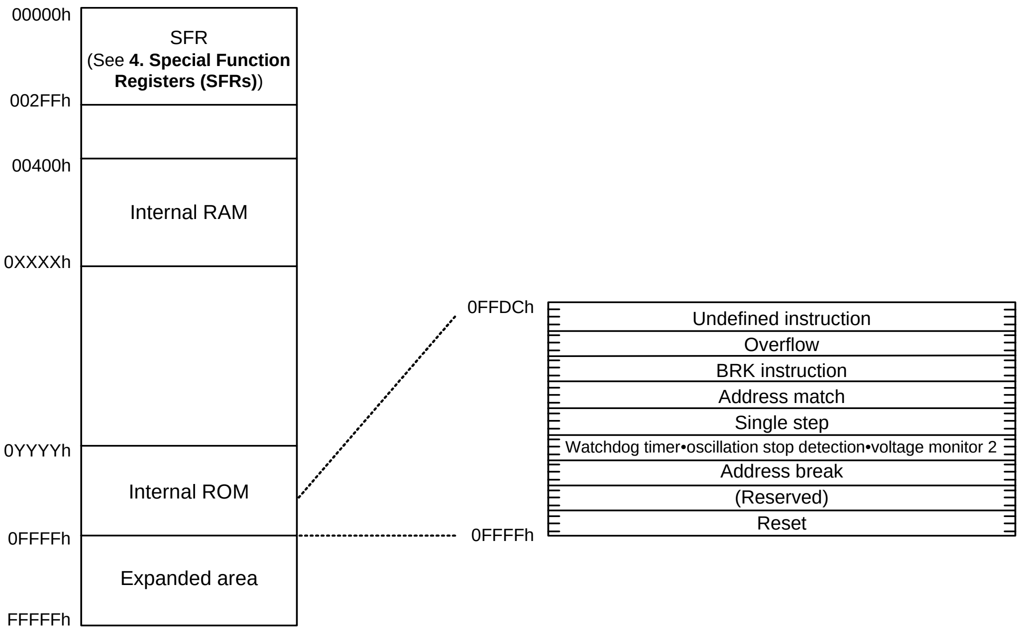
2.8.10 Reserved Bit

If necessary, set to 0. When read, the content is undefined.

3. Memory

3.1 R8C/1A Group

Figure 3.1 is a Memory Map of R8C/1A Group. The R8C/1A Group has 1 Mbyte of address space from addresses 00000h to FFFFFh.
The internal ROM is allocated lower addresses, beginning with address 0FFFFh. For example, a 16-Kbyte internal ROM area is allocated addresses 0C000h to 0FFFFh.
The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.
The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 1-Kbyte internal RAM area is allocated addresses 00400h to 007FFh. The internal RAM is used not only for storing data but also for calling subroutines and as stacks when interrupt requests are acknowledged.
Special function registers (SFRs) are allocated addresses 00000h to 002FFh. The peripheral function control registers are allocated here. All addresses within the SFR, which have nothing allocated are reserved for future use and cannot be accessed by users.



NOTE:
1. The blank regions are reserved. Do not access locations in these regions.

Part Number	Internal ROM		Internal RAM	
	Size	Address 0YYYYh	Size	Address 0XXXXh
R5F211A4SP, R5F211A4DSP, R5F211A4DD, R5F211A4NP, R5F211A4XXXSP, R5F211A4DXXXSP, R5F211A4XXXDD, R5F211A4XXXNP	16 Kbytes	0C000h	1 Kbyte	007FFh
R5F211A3SP, R5F211A3DSP, R5F211A3DD, R5F211A3NP, R5F211A3XXXSP, R5F211A3DXXXSP, R5F211A3XXXDD, R5F211A3XXXNP	12 Kbytes	0D000h	768 bytes	006FFh
R5F211A2SP, R5F211A2DSP, R5F211A2DD, R5F211A2NP, R5F211A2XXXSP, R5F211A2DXXXSP, R5F211A2XXXDD, R5F211A2XXXNP	8 Kbytes	0E000h	512 bytes	005FFh
R5F211A1SP, R5F211A1DSP, R5F211A1DD, R5F211A1XXXSP, R5F211A1DXXXSP, R5F211A1XXXDD	4 Kbytes	0F000h	384 bytes	0057Fh

Figure 3.1 Memory Map of R8C/1A Group

Table 4.4 SFR Information (4)[1]

Address	Register	Symbol	After reset
00C0h	A/D Register	AD	XXh
00C1h			XXh
00C2h			
00C3h			
00C4h			
00C5h			
00C6h			
00C7h			
00C8h			
00C9h			
00CAh			
00CBh			
00CCh			
00CDh			
00CEh			
00CFh			
00D0h			
00D1h			
00D2h			
00D3h			
00D4h	A/D Control Register 2	ADCON2	00h
00D5h			
00D6h	A/D Control Register 0	ADCON0	00000XXXb
00D7h	A/D Control Register 1	ADCON1	00h
00D8h			
00D9h			
00DAh			
00DBh			
00DCh			
00DDh			
00DEh			
00DFh			
00E0h			
00E1h	Port P1 Register	P1	XXh
00E2h			
00E3h	Port P1 Direction Register	PD1	00h
00E4h			
00E5h	Port P3 Register	P3	XXh
00E6h			
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h			
00EAh	Port P4 Direction Register	PD4	00h
00EBh			
00ECh			
00EDh			
00EEh			
00EFh			
00F0h			
00F1h			
00F2h			
00F3h			
00F4h			
00F5h			
00F6h			
00F7h			
00F8h	Port Mode Register	PMR	00h
00F9h			
00FAh			
00FBh			
00FCh	Pull-Up Control Register 0	PUR0	00XX0000b
00FDh	Pull-Up Control Register 1	PUR1	XXXXXX0Xb
00FEh	Port P1 Drive Capacity Control Register	DRR	00h
00FFh	Timer C Output Control Register	TCOUT	00h
01B3h	Flash Memory Control Register 4	FMR4	01000000b
01B4h			
01B5h	Flash Memory Control Register 1	FMR1	1000000Xb
01B6h			
01B7h	Flash Memory Control Register 0	FMR0	00000001b
0FFFFh	Optional Function Select Register	OFS	(2)

X: Undefined

NOTES:

1. Blank regions, 0100h to 01B2h and 01B8h to 02FFh are all reserved. Do not access locations in these regions.
2. The OFS register cannot be changed by a user program. Use a flash programmer to write to it.

Table 5.3 A/D Converter Characteristics

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
–	Resolution		V_{ref} = V_{CC}	–	–	10	Bits
–	Absolute accuracy	10-bit mode	ϕ_{AD} = 10 MHz, V_{ref} = V_{CC} = 5.0 V	–	–	±3	LSB
		8-bit mode	ϕ_{AD} = 10 MHz, V_{ref} = V_{CC} = 5.0 V	–	–	±2	LSB
		10-bit mode	ϕ_{AD} = 10 MHz, V_{ref} = V_{CC} = 3.3 V(3)	–	–	±5	LSB
		8-bit mode	ϕ_{AD} = 10 MHz, V_{ref} = V_{CC} = 3.3 V(3)	–	–	±2	LSB
R_{ladder}	Resistor ladder		V_{ref} = V_{CC}	10	–	40	kΩ
t_{conv}	Conversion time	10-bit mode	ϕ_{AD} = 10 MHz, V_{ref} = V_{CC} = 5.0 V	3.3	–	–	µs
		8-bit mode	ϕ_{AD} = 10 MHz, V_{ref} = V_{CC} = 5.0 V	2.8	–	–	µs
V_{ref}	Reference voltage			2.7	–	Vcc	V
V_{IA}	Analog input voltage(4)			0	–	AVcc	V
–	A/D operating clock frequency(2)	Without sample and hold		0.25	–	10	MHz
		With sample and hold		1	–	10	MHz

NOTES:
1. V_{CC} = AV_{CC} = 2.7 to 5.5 V at T_{opr} = -20 to 85 °C / -40 to 85 °C, unless otherwise specified.
2. If f1 exceeds 10 MHz, divide f1 and ensure the A/D operating clock frequency (ϕ_{AD}) is 10 MHz or below.
3. If AVcc is less than 4.2 V, divide f1 and ensure the A/D operating clock frequency (ϕ_{AD}) is f1/2 or below.
4. When the analog input voltage is over the reference voltage, the A/D conversion result will be 3FFh in 10-bit mode and FFh in 8-bit mode.

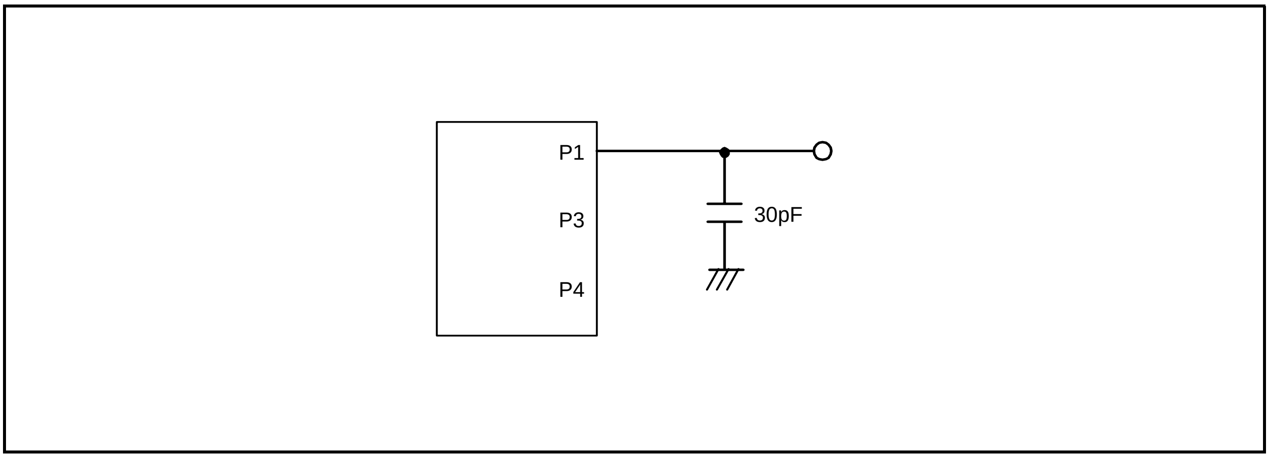


Figure 5.1 Port P1, P3, and P4 Measurement Circuit

Table 5.8 Reset Circuit Electrical Characteristics (When Using Voltage Monitor 1 Reset)

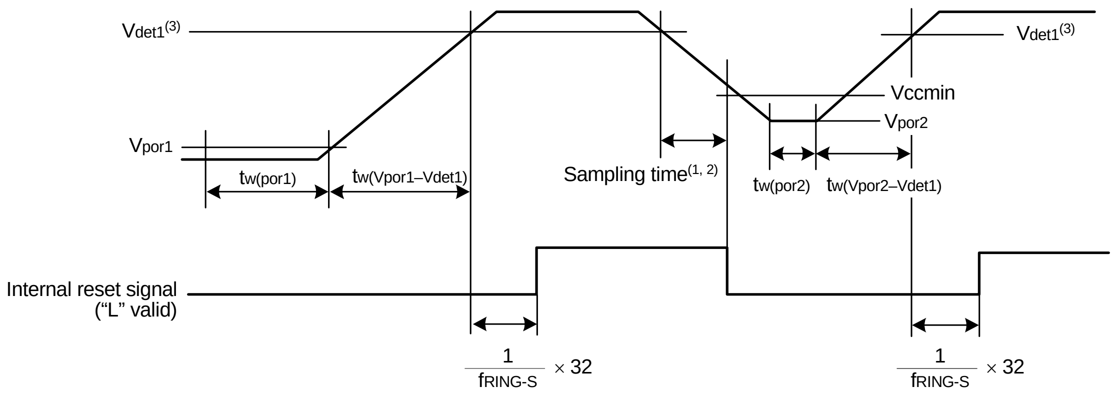
Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{por2}	Power-on reset valid voltage	-20°C ≤ Topr ≤ 85°C	–	–	V_{det1}	V
$t_{w(Vpor2-Vdet1)}$	Supply voltage rising time when power-on reset is deasserted(1)	-20°C ≤ Topr ≤ 85°C, $t_{w(por2)} \geq 0s$(3)	–	–	100	ms

NOTES:
1. This condition is not applicable when using with Vcc ≥ 1.0 V.
2. When turning power on after the time to hold the external power below effective voltage (V_{por1}) exceeds10 s, refer to **Table 5.9 Reset Circuit Electrical Characteristics (When Not Using Voltage Monitor 1 Reset)**.
3. $t_{w(por2)}$ is the time to hold the external power below effective voltage (V_{por2}).

Table 5.9 Reset Circuit Electrical Characteristics (When Not Using Voltage Monitor 1 Reset)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{por1}	Power-on reset valid voltage	-20°C ≤ Topr ≤ 85°C	–	–	0.1	V
$t_{w(Vpor1-Vdet1)}$	Supply voltage rising time when power-on reset is deasserted	0°C ≤ Topr ≤ 85°C, $t_{w(por1)} \geq 10$ s(2)	–	–	100	ms
$t_{w(Vpor1-Vdet1)}$	Supply voltage rising time when power-on reset is deasserted	-20°C ≤ Topr < 0°C, $t_{w(por1)} \geq 30$ s(2)	–	–	100	ms
$t_{w(Vpor1-Vdet1)}$	Supply voltage rising time when power-on reset is deasserted	-20°C ≤ Topr < 0°C, $t_{w(por1)} \geq 10$ s(2)	–	–	1	ms
$t_{w(Vpor1-Vdet1)}$	Supply voltage rising time when power-on reset is deasserted	0°C ≤ Topr ≤ 85°C, $t_{w(por1)} \geq 1$ s(2)	–	–	0.5	ms

NOTES:
1. When not using voltage monitor 1, use with Vcc≥ 2.7 V.
2. $t_{w(por1)}$ is the time to hold the external power below effective voltage (V_{por1}).



NOTES:
1. Hold the voltage inside the MCU operation voltage range (Vccmin or above) within the sampling time.
2. The sampling clock can be selected. Refer to **7. Voltage Detection Circuit** for details.
3. V_{det1} indicates the voltage detection level of the voltage detection 1 circuit. Refer to **7. Voltage Detection Circuit** for details.

Figure 5.3 Reset Circuit Electrical Characteristics

Table 5.10 High-Speed On-Chip Oscillator Circuit Electrical Characteristics

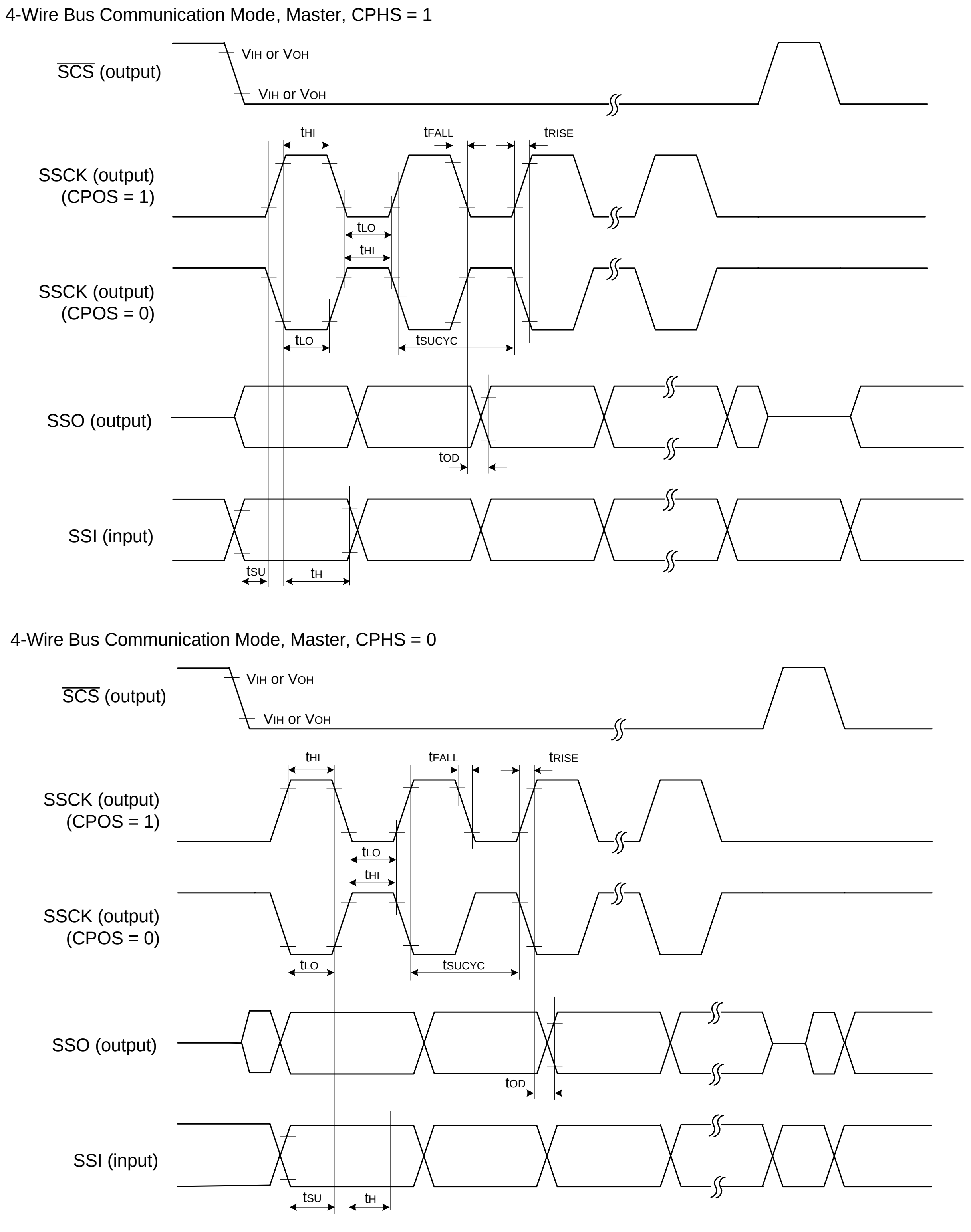
Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
–	High-speed on-chip oscillator frequency when the reset is deasserted	V_{CC} = 5.0 V, T_{opr} = 25 °C	–	8	–	MHz
–	High-speed on-chip oscillator frequency temperature • supply voltage dependence(2)	0 to +60 °C/5 V ± 5 %(3)	7.76	–	8.24	MHz
		-20 to +85 °C/2.7 to 5.5 V(3)	7.68	–	8.32	MHz
		-40 to +85 °C/2.7 to 5.5 V(3)	7.44	–	8.32	MHz

NOTES:
1. The measurement condition is V_{CC} = 5.0 V and T_{opr} = 25 °C.
2. Refer to **10.6.4 High-Speed On-Chip Oscillator Clock** for notes on high-speed on-chip oscillator clock.
3. The standard value shows when the HRA1 register is assumed as the value in shipping and the HRA2 register value is set to 00h.

Table 5.11 Power Supply Circuit Timing Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
$t_{d(P-R)}$	Time for internal power supply stabilization during power-on(2)		1	–	2000	µs
$t_{d(R-S)}$	STOP exit time(3)		–	–	150	µs

NOTES:
1. The measurement condition is V_{CC} = 2.7 to 5.5 V and T_{opr} = 25 °C.
2. Waiting time until the internal power supply generation circuit stabilizes during power-on.
3. Time until CPU clock supply starts after the interrupt is acknowledged to exit stop mode.



4-Wire Bus Communication Mode, Master, CPHS = 1

4-Wire Bus Communication Mode, Master, CPHS = 0

CPHS, CPOS: Bits in SSMR register

Figure 5.4 I/O Timing of Clock Synchronous Serial I/O with Chip Select (Master)

Table 5.15 Electrical Characteristics (2) [Vcc = 5 V] (Topr = -40 to 85 °C, unless otherwise specified.)

Symbol	Parameter	Condition		Standard			Unit
				Min.	Typ.	Max.	
I_{CC}	Power supply current (V_{CC} = 3.3 to 5.5 V) Single-chip mode, output pins are open, other pins are V_{SS}, A/D converter is stopped	High-speed mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	9	15	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	8	14	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	5	–	mA
		Medium-speed mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	4	–	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3	–	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	2	–	mA
		High-speed on-chip oscillator mode	Main clock off High-speed on-chip oscillator on = 8 MHz Low-speed on-chip oscillator on = 125 kHz No division	–	4	8	mA
			Main clock off High-speed on-chip oscillator on = 8 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	1.5	–	mA
		Low-speed on-chip oscillator mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8 FMR47 = 1	–	110	300	µA
		Wait mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = 0	–	40	80	µA
		Wait mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = 0	–	38	76	µA
		Stop mode	Main clock off, Topr = 25 °C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = 0	–	0.8	3.0	µA

Table 5.21 Electrical Characteristics (3) [V_{CC} = 3V]

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output “H” voltage	Except X_{OUT}	I_{OH} = -1 mA		V_{CC} – 0.5	–	V_{CC}	V
		X_{OUT}	Drive capacity HIGH	I_{OH} = -0.1 mA	V_{CC} – 0.5	–	V_{CC}	V
			Drive capacity LOW	I_{OH} = -50 µA	V_{CC} – 0.5	–	V_{CC}	V
V_{OL}	Output “L” voltage	Except P1_0 to P1_3, X_{OUT}	I_{OL} = 1 mA		–	–	0.5	V
		P1_0 to P1_3	Drive capacity HIGH	I_{OL} = 2 mA	–	–	0.5	V
			Drive capacity LOW	I_{OL} = 1 mA	–	–	0.5	V
		X_{OUT}	Drive capacity HIGH	I_{OL} = 0.1 mA	–	–	0.5	V
			Drive capacity LOW	I_{OL} = 50 µA	–	–	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$, $\overline{INT1}$, $\overline{INT3}$, $\overline{KI0}$, $\overline{KI1}$, $\overline{KI2}$, $\overline{KI3}$, CNTR0, CNTR1, TCIN, RXD0			0.2	–	0.8	V
		$\overline{RESET}$			0.2	–	1.8	V
I_{IH}	Input “H” current		VI = 3 V		–	–	4.0	µA
I_{IL}	Input “L” current		VI = 0 V		–	–	-4.0	µA
R_{PULLUP}	Pull-up resistance		VI = 0 V		66	160	500	kΩ
R_{fXIN}	Feedback resistance	XIN			–	3.0	–	MΩ
f_{RING-S}	Low-speed on-chip oscillator frequency				40	125	250	kHz
V_{RAM}	RAM hold voltage		During stop mode		2.0	–	–	V

NOTE:

1. V_{CC} = 2.7 to 3.3 V at T_{opr} = -20 to 85 °C / -40 to 85 °C, f(XIN) = 10 MHz, unless otherwise specified.

Table 5.22 Electrical Characteristics (4) [Vcc = 3 V] (Topr = -40 to 85 °C, unless otherwise specified.)

Symbol	Parameter	Condition		Standard			Unit
				Min.	Typ.	Max.	
ICC	Power supply current (VCC = 2.7 to 3.3 V) Single-chip mode, output pins are open, other pins are VSS, A/D converter is stopped	High-speed mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	8	13	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	7	12	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	5	–	mA
		Medium-speed mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3	–	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	2.5	–	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	1.6	–	mA
		High-speed on-chip oscillator mode	Main clock off High-speed on-chip oscillator on = 8 MHz Low-speed on-chip oscillator on = 125 kHz No division	–	3.5	7.5	mA
			Main clock off High-speed on-chip oscillator on = 8 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	1.5	–	mA
		Low-speed on-chip oscillator mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8 FMR47 = 1	–	100	280	µA
		Wait mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = 0	–	37	74	µA
		Wait mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = 0	–	35	70	µA
		Stop mode	Main clock off, Topr = 25 °C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = 0	–	0.7	3.0	µA

Table 5.26 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	300	–	ns
$t_{W(CKH)}$	CLKi input “H” width	150	–	ns
$t_{W(CKL)}$	CLKi input “L” width	150	–	ns
$t_{d(C-Q)}$	TXDi output delay time	–	80	ns
$t_{h(C-Q)}$	TXDi hold time	0	–	ns
$t_{su(D-C)}$	RXDi input setup time	70	–	ns
$t_{h(C-D)}$	RXDi input hold time	90	–	ns

i = 0 or 1

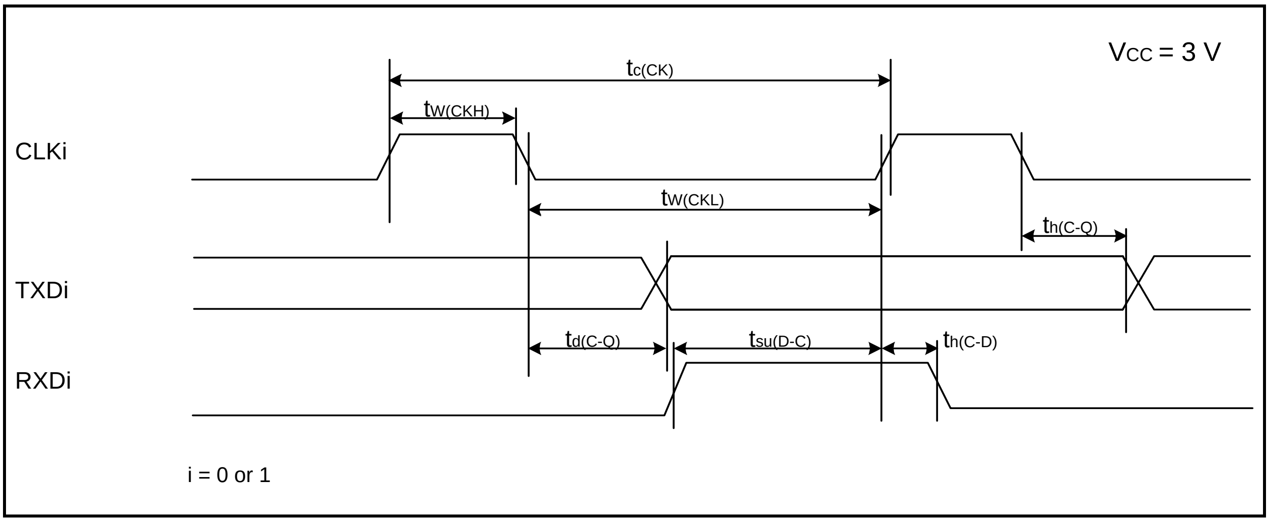


Figure 5.16 Serial Interface Timing Diagram when V_{CC} = 3 V

Table 5.27 External Interrupt $\overline{\text{INT0}}$ Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{W(INH)}$	$\overline{\text{INT0}}$ input “H” width	380[1]	–	ns
$t_{W(INL)}$	$\overline{\text{INT0}}$ input “L” width	380[2]	–	ns

NOTES:
1. When selecting the digital filter by the $\overline{\text{INT0}}$ input filter select bit, use an $\overline{\text{INT0}}$ input HIGH width of either (1/digital filter clock frequency x 3) or the minimum value of standard, whichever is greater
2. When selecting the digital filter by the $\overline{\text{INT0}}$ input filter select bit, use an $\overline{\text{INT0}}$ input LOW width of either (1/digital filter clock frequency x 3) or the minimum value of standard, whichever is greater

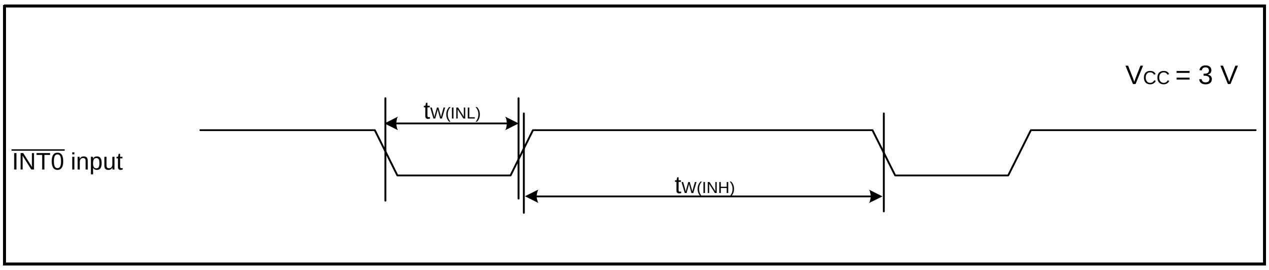
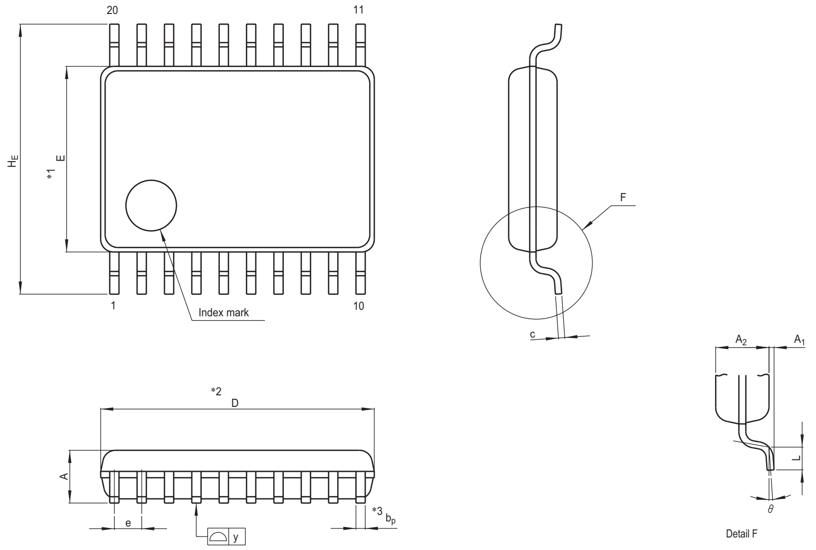


Figure 5.17 External Interrupt $\overline{\text{INT0}}$ Input Timing Diagram when V_{CC} = 3 V

Package Dimensions

Diagrams showing the latest package dimensions and mounting information are available in the “Packages” section of the Renesas Technology website.

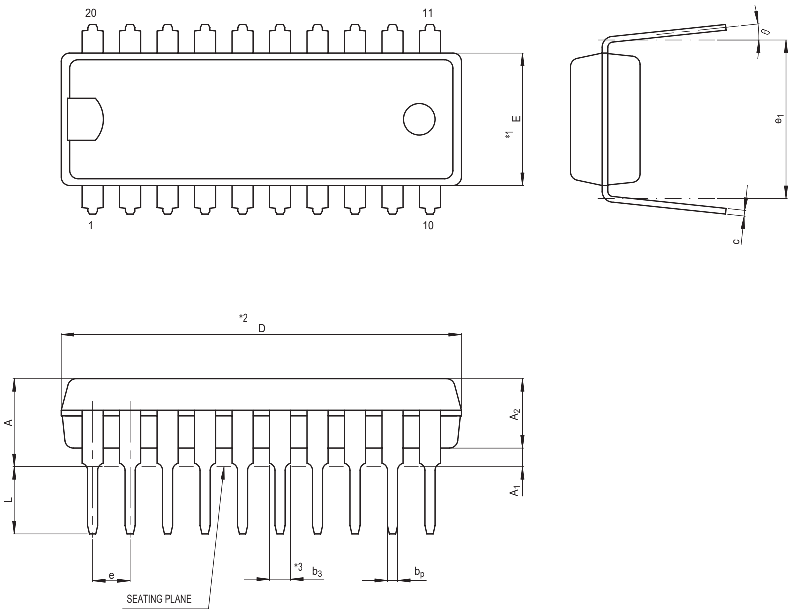
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LSSOP20-4.4x6.5-0.65	PLSP0020JB-A	20P2F-A	0.1g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	6.4	6.5	6.6
E	4.3	4.4	4.5
A_2	—	1.15	—
A	—	—	1.45
A_1	0	0.1	0.2
b_p	0.17	0.22	0.32
c	0.13	0.15	0.2
θ	0°	—	10°
H_E	6.2	6.4	6.6
e	0.53	0.65	0.77
y	—	—	0.10
L	0.3	0.5	0.7

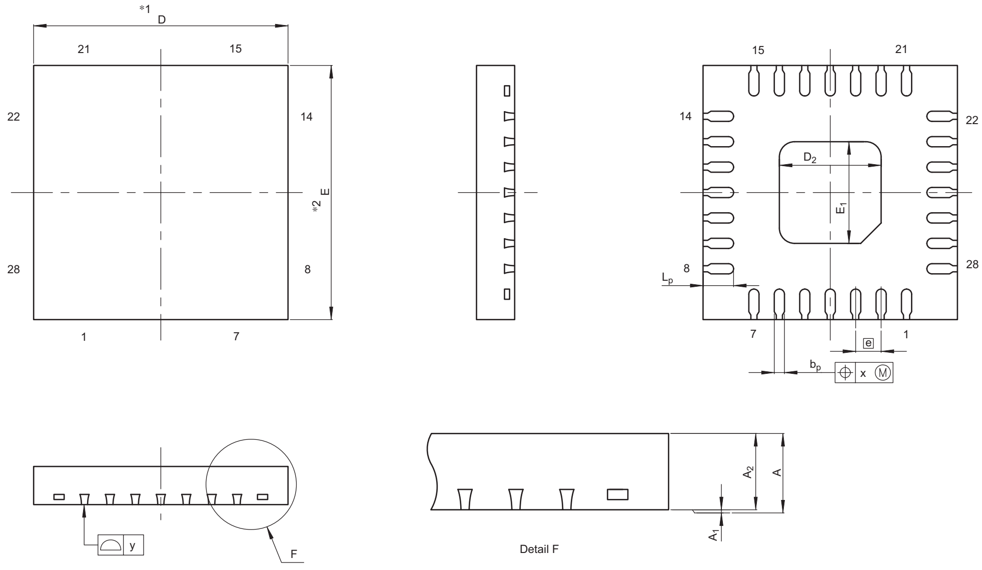
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-SDIP20-6.3x19-1.78	PRDP0020BA-A	20P4B	1.0g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
e_1	7.32	7.62	7.92
D	18.8	19.0	19.2
E	6.15	6.3	6.45
A	—	—	4.5
A_1	0.51	—	—
A_2	—	3.3	—
b_p	0.38	0.48	0.58
b_3	0.9	1.0	1.3
c	0.22	0.27	0.34
θ	0°	—	15°
e	1.528	1.778	2.028
L	3.0	—	—

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-HWQFN28-5x5-0.50	PWQN0028KA-B	28PJW-B	0.05g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	4.9	5.0	5.1
E	4.9	5.0	5.1
A_2	—	0.75	—
A	—	—	0.8
A_1	0	0	0.05
b_p	0.15	0.2	0.25
$\boxed{e}$	—	0.5	—
L_p	0.5	0.6	0.7
x	—	—	0.05
y	—	—	0.05
D_2	—	2.0	—
E_1	—	2.0	—

REVISION HISTORY	R8C/1A Group, R8C/1B Group Datasheet

Rev.	Date	Description	
		Page	Summary
1.30	Oct 03, 2006	1	1.1 “portable equipment” added
		2, 3	Table 1.1, Table 1.2; Specification Interrupts: “Internal: 9 sources” → “Internal: 11 sources”
		24	Table 5.2; Parameter: System clock added
		45	Package Dimensions; PWQN0028KA-B revised
1.40	Dec 08, 2006	20	Table 4.1; 000Fh: After reset “000XXXXXb” → “00X11111b”
		24	Table 19.2; Parameter: OCD2 = 1 On-chip oscillator clock selected revised

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